

BONDIT™ B-575

Adhesive System

Bonds dissimilar materials

A fast-cure epoxy adhesive for bonding dissimilar materials such as glass, ceramic, metals, wood and plastics – acrylic, polycarbonate, PEEK, polyolefin and many more polymers. Excellent lapshear and peel strength, with high initial bond strength.

High performance

Excellent chemical resistance, very high tensile strength, even with ambient cure. High thermal stability in a rugged semi-flexible system. The product is also available in the filled (thixotropic) as well as electrically and thermally conductive versions (silver-filled).

Easy to use

Two-part, primerless, ambient cure system with very low HAZMAT impact for work environment. Available in handheld and pneumatic gun actuated cartridges, quarts, gallons and drums.

Harsh environments

Marine,
Civil Engineering,
Downhole oil,
Underwater,
Electronic,
Mining,
Industrial,
Automotive.





BONDIT™ B-575

Description

BONDIT™ B-575 is a two-part, very high strength, 100% solids, room-temperature curing semi-flexible epoxy resin system. Especially designed for adhesive applications in bonding to a wide range of engineering plastics, including polyolefin and metals, glass, ceramic, composite and wood. Typical example of lapshear bond strength is 1100 PSI for PEEK-to-PEEK and PEEK-to-Steel substrates. B-575 handles harsh environments easily and is effective against moisture, salt water, acids, alkalis, oils, and detergents. B-575 has high thermal stability and offers good corrosion resistance.

The semi-flexible properties of B-575 permits assembly of materials with dissimilar thermal expansion and survive thermal cycling. Likewise mechanical vibration, shock and impact are easily absorbed by B-575 and protect surfaces and bonded assemblies.

Mixing, Curing, and Storage

Apply B-575 by static mixer, brush or roller. B-575 is very easy to use with low HAZMAT impact as a 100% solids epoxy system—no solvents or VOC problems.

Ambient cure: 40 minute pot life; 40 min full cure with 10 gm mix or static mixer. Thin film ambient set time of 45 minutes and cure of 60 minutes. Thermal cure at 135degF is approximately 10 minute, at 200degF cure is approximately 90 seconds. In 100gr quantity B-575 is exothermic which will shorten pot life. Mix part A with part B, 10:1 ratio by volume or weight. Surface prep by abrading or grit blasting substrates with #100 AlOx followed by degrease and/or alcohol wipe.

The usable shelf life of unopened containers of **BONDIT™ B-575** resin is one year, and should be stored in cool, dry place. When not in use, containers should be kept tightly closed.

BONDIT™ B-575 is available in side-by-side handheld and pneumatic actuated gun cartridges, quarts, gallons, pails and drums. Custom packaging, such as premixed and degassed frozen cartridges, is also available.

Typical Properties

Property	
Color	Clear with slight amber
Viscosity	~9500 cps
Tensile strength	Ambient Cure
Peak stress	7693 PSI
Break stress	7418 PSI
Elongation at break	9.2%
Yield stress	7693 PSI
Elongation at yield	8.6%

Information

For further information, engineering support and sales service, contact **RELTEK** sales office.